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- Member of the Texas Instruments Widebus™ Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 2 V at V_{CC} = 3.3 V, T_A = 25°C
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

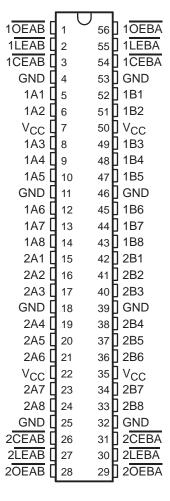
description

This 16-bit registered transceiver is designed for low-voltage (3.3-V) V_{CC} operation.

The SN74LVC16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (\overline{CEAB}) input must be low in order to enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low,

DGG OR DL PACKAGE (TOP VIEW)



the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the CEBA, LEBA, and OEBA inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74LVC16543 is characterized for operation from −40°C to 85°C.



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FUNCTION TABLE† (each 8-bit section)

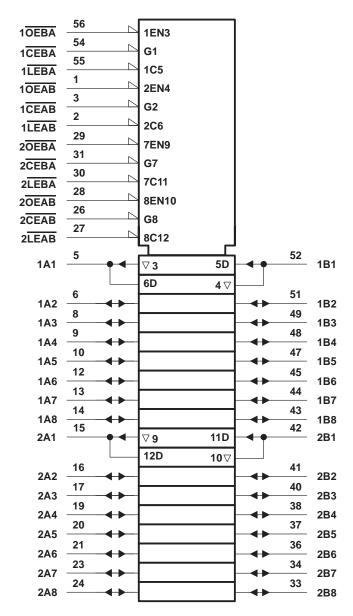
	INPUTS					
CEAB	LEAB	OEAB	Α	В		
Н	Х	Х	Χ	Z		
Х	Χ	Н	X	Z		
L	Н	L	Χ	в ₀ ‡		
L	L	L	L	L		
L	L	L	Н	Н		

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.



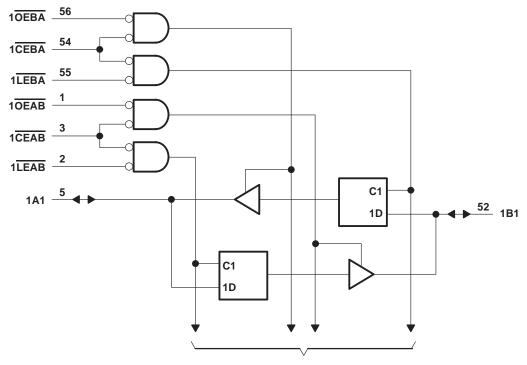
[‡] Output level before the indicated steady-state input conditions were established

logic symbol†

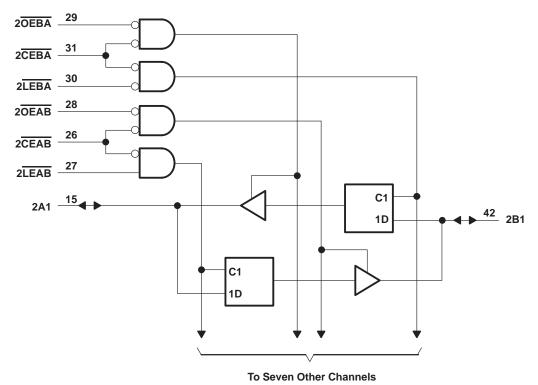


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels



TEXAS INSTRUMENTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} 0.5 V to 4.6 V
nput voltage range, V _I : Except I/O ports (see Note 1)
I/O ports (see Notes 1 and 2)
Dutput voltage range, V_O (see Notes 1 and 2)
nput clamp current, I_{IK} ($V_I < 0$) –50 mA
Dutput clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ± 50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) ± 50 mA
Continuous current through V _{CC} or GND ±100 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): DGG package
DL package 1.4 W
Storage temperature range, T _{stg} –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
 For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology
 Data Book, literature number SCBD002B.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	V
VIH	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
V_{IL}	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V
٧ _I	Input voltage		0	VCC	V
VO	Output voltage		0	VCC	V
	High-level output current	V _{CC} = 2.7 V		-12	mA
Іон		V _{CC} = 3 V		-24	IIIA
lo.	Loughy aloute of automat	V _{CC} = 2.7 V		12	mA
lor	Low-level output current VCC = 3 V			24	ША
Δt/Δν	Input transition rise or fall rate		0	10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



SN74LVC16543 **16-BIT REGISTERED TRANSCEIVER** WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAI	RAMETER	TEST CO	ONDITIONS	v _{cc} †	MIN	TYP [‡]	MAX	UNIT
l f		$I_{OH} = -100 \mu\text{A}$		MIN to MAX	VCC-0	.2		
		I _{OH} = -12 mA		2.7 V	2.2			V
VOH		10H = - 12 111A		3 V	2.4			V
		$I_{OH} = -24 \text{ mA}$	$I_{OH} = -24 \text{ mA}$		2			
		$I_{OL} = 100 \mu A$		MIN to MAX			0.2	
VOL		I _{OL} = 12 mA		2.7 V			0.4	V
		I _{OL} = 24 mA		3 V			0.55	
Ц	Control inputs	$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ
lia i s	A or P porto	V _I = 0.8 V		3 V	75			
l(hold)	A or B ports	V _I = 2 V]	-75			μΑ
I _{OZ} §		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ
ICC		$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μΑ
∆lcc		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			500	μΑ
Ci	Control inputs	$V_I = V_{CC}$ or GND		3.3 V		3		pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		7	·	pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
		MIN	MAX	MIN	MAX	
t _W	Pulse duration, LE or CE low	4		4		ns
t _{su}	Setup time, Data before LE, CE	2		2		ns
th	Hold time, Data after LE, CE	2		2		ns

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	(OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
	(INPUT)		MIN	MAX	MIN	MAX	
t _{pd}	A or B	B or A	1.5	8	1.5	9	ns
t _{pd}	LE	A or B	1.5	9	1.5	10	ns
t _{en}	CE	A or B	1.5	9	1.5	10	ns
^t dis	CE	A or B	1.5	9	1.5	10	ns
t _{en}	ŌĒ	A or B	1.5	8.5	1.5	9.5	ns
t _{dis}	ŌĒ	A or B	1.5	8.5	1.5	9.5	ns

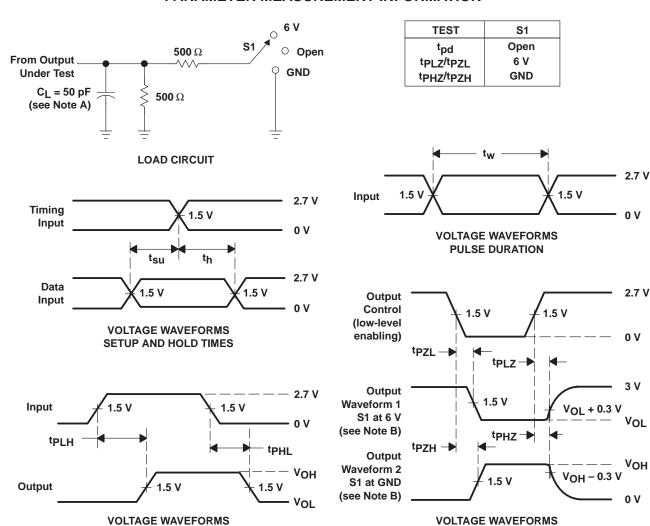


 $[\]ddagger$ All typical values are at V_{CC} = = 3.3 V, T_A = 25°C. § For I/O ports, the parameter I_{OZ} includes the input leakage current.

operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

PARAMETER		TEST CON	TYP	UNIT		
C _{pd} Power dissipation capacitance per transceiver	Dower discipation conscitance per transcriver	Outputs enabled	C 50F	f 40 MI I-	21	~F
	Outputs disabled	$C_L = 50 \text{ pF}, f = 10 \text{ MH}$	f = 10 MHz	3.5	pF	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq 2.5~ns$, $t_f \leq 2.5~ns$.

ENABLE AND DISABLE TIMES

- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.

PROPAGATION DELAY TIMES

- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.



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